This specification defines the method for bare die packing and part number identification. Example: Small Signal NPN High Voltage Transistor Die, 2N3439, Tray (Waffle) Package.

### Bare Die Part Numbering System

- **Central Process Number**
  - (5-7 Alpha/Numeric)
  - CPxxx = Transistor
  - CPZxx = Zener Diode
  - CPDxx = Diode
  - CPQxx = TRIAC
  - CPSxx = SCR

- **Packaging Method**
  - **CM** = Singulated bare die, 100% electrically tested, 100% visually inspected, reject die removed, tray (waffle) package
  - **CT** = Singulated bare die, 100% electrically tested, reject die removed, tray (waffle) package
  - **WN** = Wafer form, 100% electrically tested, reject die inked
  - **WR** = Wafer form, 100% electrically tested, sawn and mounted on adhesive membrane and plastic ring, reject die inked
  - **WS** = Wafer form, 100% electrically tested, sawn and mounted on adhesive membrane and metal frame, reject die inked
  - **WS*** = By special order only. Please contact Central sales representative at 631-435-1110.

Visit the Central website for a complete listing of all available WR and WS specifications:

[www.centralsemi.com/bdspecs](http://www.centralsemi.com/bdspecs)
BARE DIE PACKING OPTIONS

BARE DIE IN TRAY (WAFFLE) PACK
CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)

UNSAWN WAFER
WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)

SAWN WAFER ON PLASTIC RING
WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.

Visit the Central website for a complete listing of specifications:
www.centralsemi.com/bds specs
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- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

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